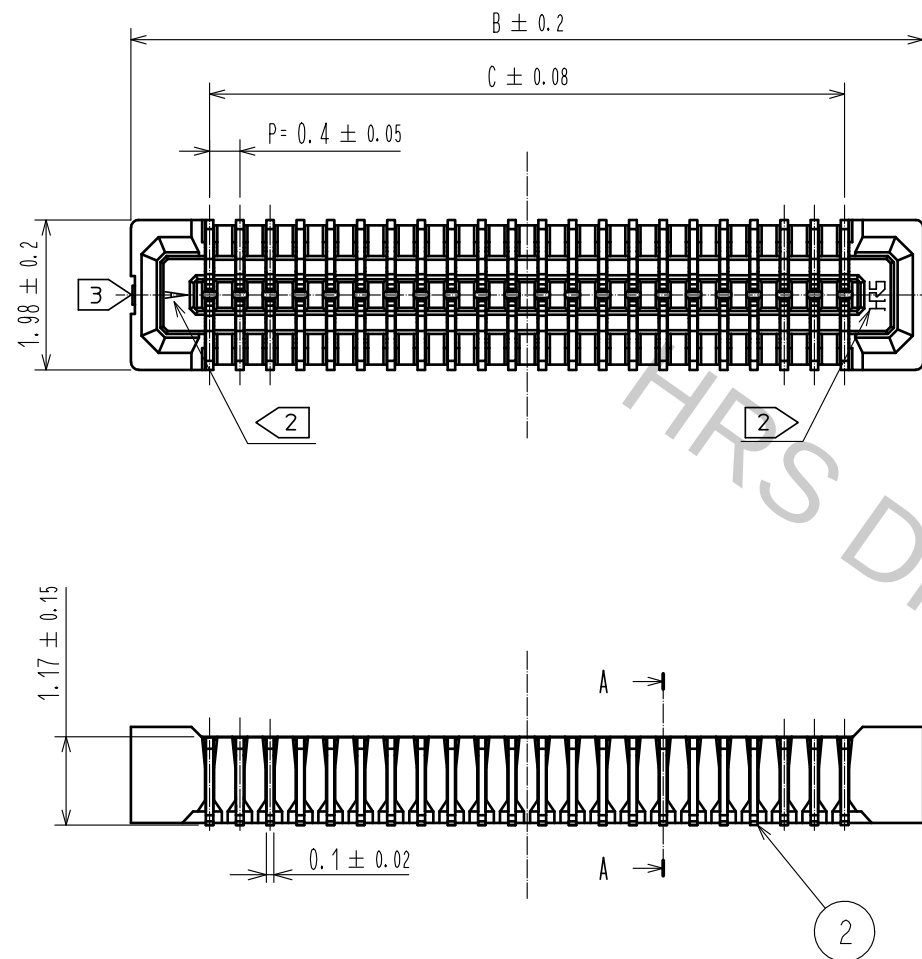
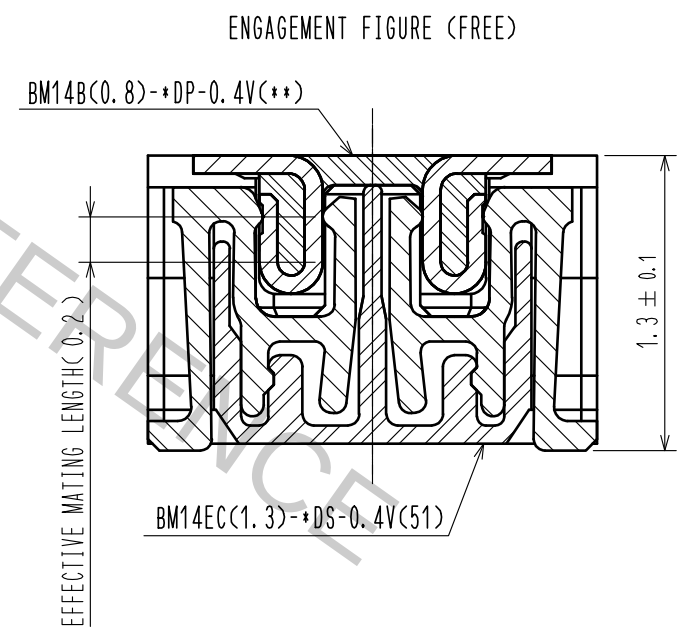
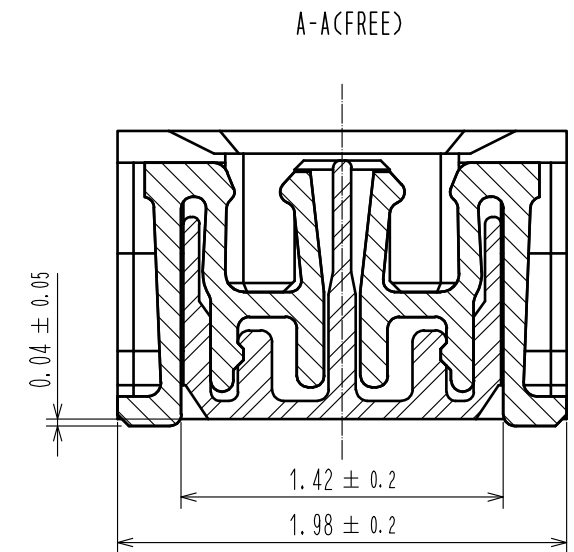


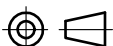


NOTE) 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.
3. GATE POSITION IS INDICATED IN APPROX POSITION SHOWN.

PART No.	CODE No.	B	C
BM14EC(1.3)-14DS-0.4V(51)	-	4.48	2.4
BM14EC(1.3)-16DS-0.4V(51)	CL684-8180-0-51	4.88	2.8
BM14EC(1.3)-24DS-0.4V(51)	-	6.48	4.4
BM14EC(1.3)-28DS-0.4V(51)	-	7.28	5.2
BM14EC(1.3)-34DS-0.4V(51)	-	8.48	6.4
BM14EC(1.3)-44DS-0.4V(51)	CL684-8155-3-51	10.48	8.4
BM14EC(1.3)-54DS-0.4V(51)	CL684-8157-9-51	12.48	10.4
BM14EC(1.3)-64DS-0.4V(51)	-	14.48	12.4

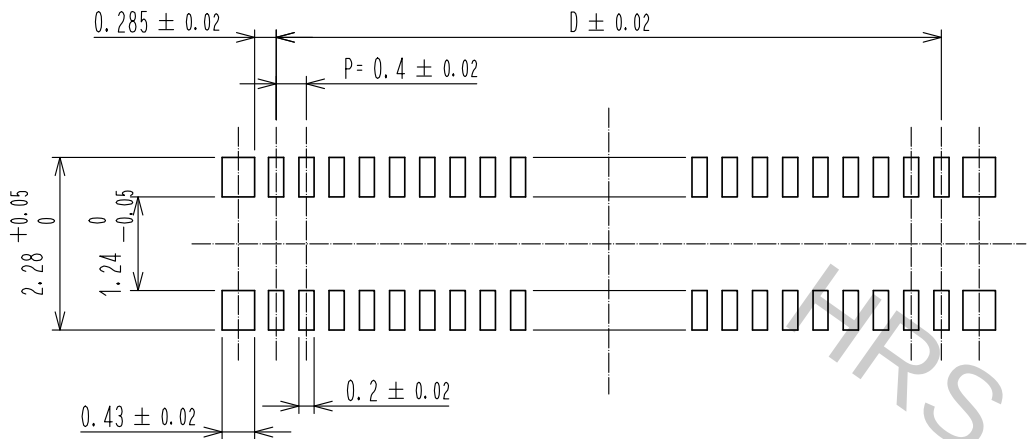


2	PHOSPHOR BRONZE	CONTACT AREA : GOLD 0.05 μm MIN.		6	PS	CLEAR (REINFORCEMENT COLLAR)	
		SMT LEAD : GOLD 0.05 μm MIN.		5	PS	BLACK (PLASTIC REEL)	
		UNDERPLATING : NICKEL 1 μm MIN.		4	POLYESTER	CLEAR (COVER TAPE)	
1	LCP	UL94 V-0, BLACK		3	PS	CLEAR (EMBOSSED CARRIER TAPE)	
NO.	MATERIAL	FINISH . REMARKS			NO.	MATERIAL	FINISH . REMARKS

UNITS mm		SCALE 10 : 1		COUNT 3	DESCRIPTION OF REVISIONS DIS-H-00002669	DESIGNED NY. YAMASHIRO	CHECKED TS. MIYAZAKI	DATE 17. 03. 07

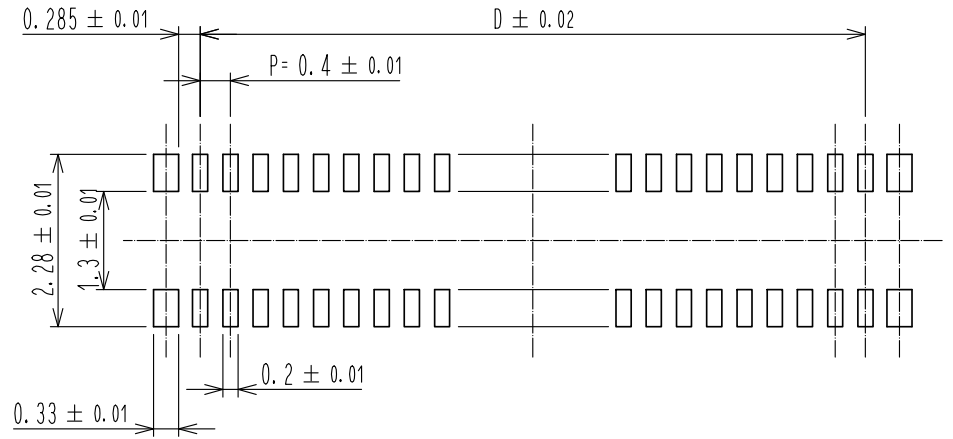
	HIROSE ELECTRIC CO., LTD.	APPROVED : KH. IKEDA	10. 04. 23	DRAWING NO.	EDC3-327823-01		
		CHECKED : TS. MIYAZAKI	10. 04. 23	PART NO.	BM14EC(1.3)-*DS-0.4V(51)		
		DESIGNED : TR. YUNOKI	10. 04. 23	CODE NO.	CL684		
		DRAWN : YN. SAKAMOTO	10. 04. 22	  			

◆ RECOMMENDED PCB LAYOUT



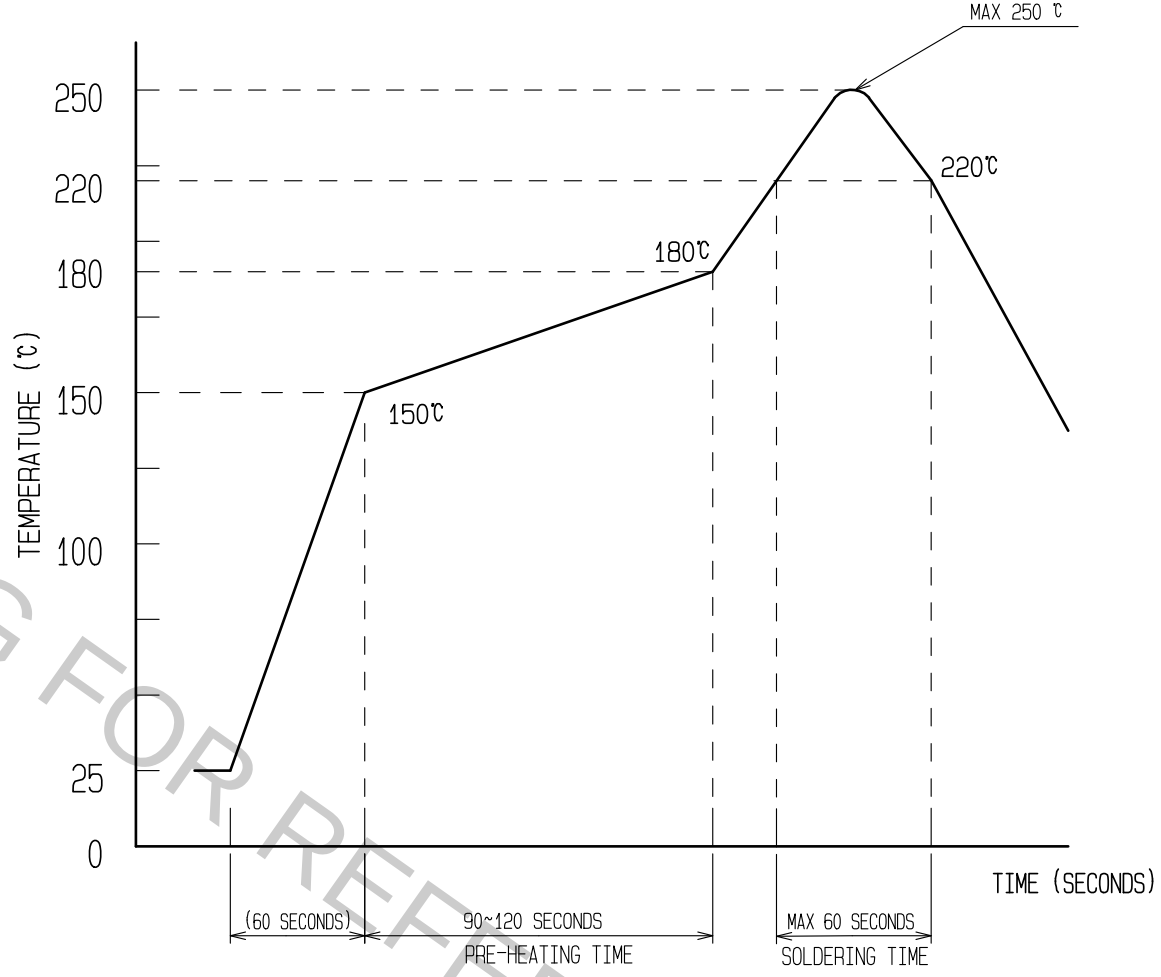
◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm



PART No.	D
BM14EC(1.3)-14DS-0.4V(51)	1.6
BM14EC(1.3)-16DS-0.4V(51)	2.0
BM14EC(1.3)-24DS-0.4V(51)	3.6
BM14EC(1.3)-28DS-0.4V(51)	4.4
BM14EC(1.3)-34DS-0.4V(51)	5.6
BM14EC(1.3)-44DS-0.4V(51)	7.6
BM14EC(1.3)-54DS-0.4V(51)	9.6
BM14EC(1.3)-64DS-0.4V(51)	11.6

4> RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



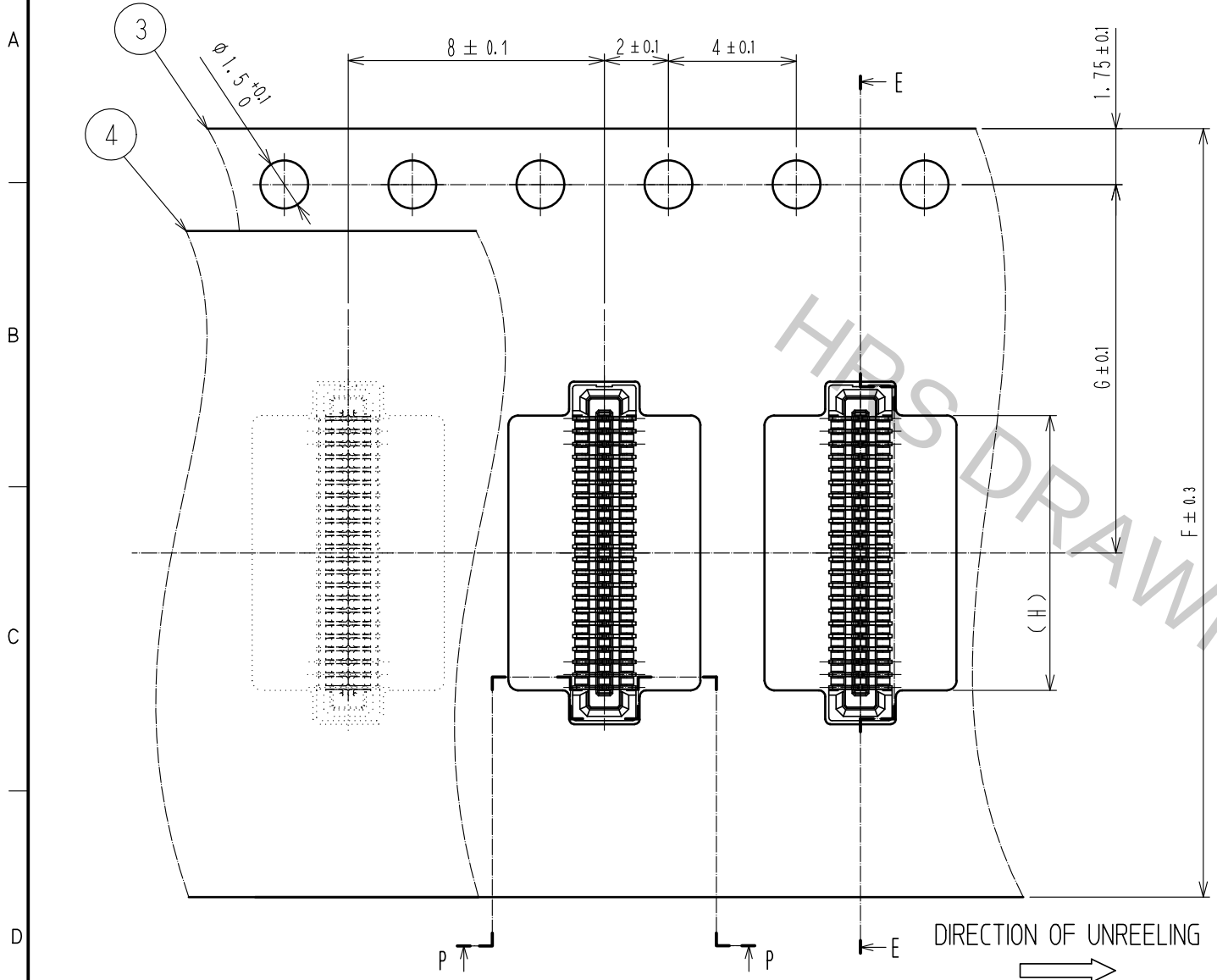
REFLOW METHOD: IR REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
1) REFLOW TIME
DURATION ABOVE 220°C, 60 SEC. MAX.
(PEAK TEMPERATURE: 250°C MAX)
2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 sec.

4> THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

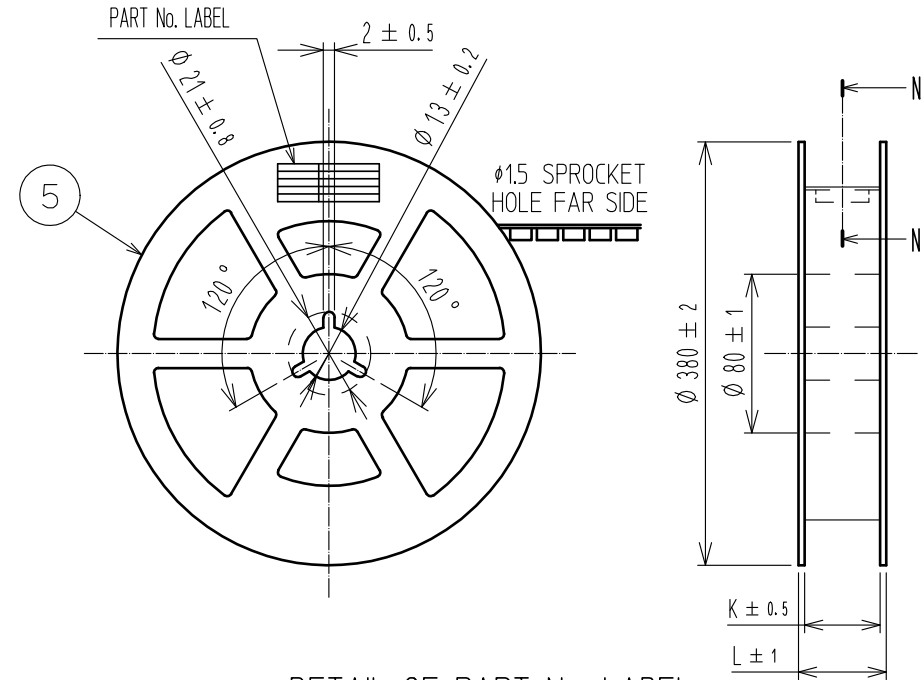
HRS	DRAWING NO.	EDC3-327823-01	
	PART NO.	BM14EC(1.3)-*DS-0.4V(51)	
	CODE NO.	CL684	2/3

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EMBOSSED CARRIER TAPE PACKAGING (5:1)



STYLE AND DIMENTION OF REEL (FREE)

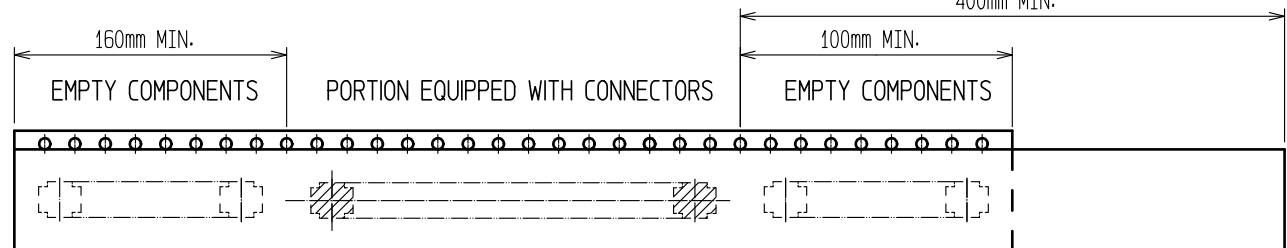
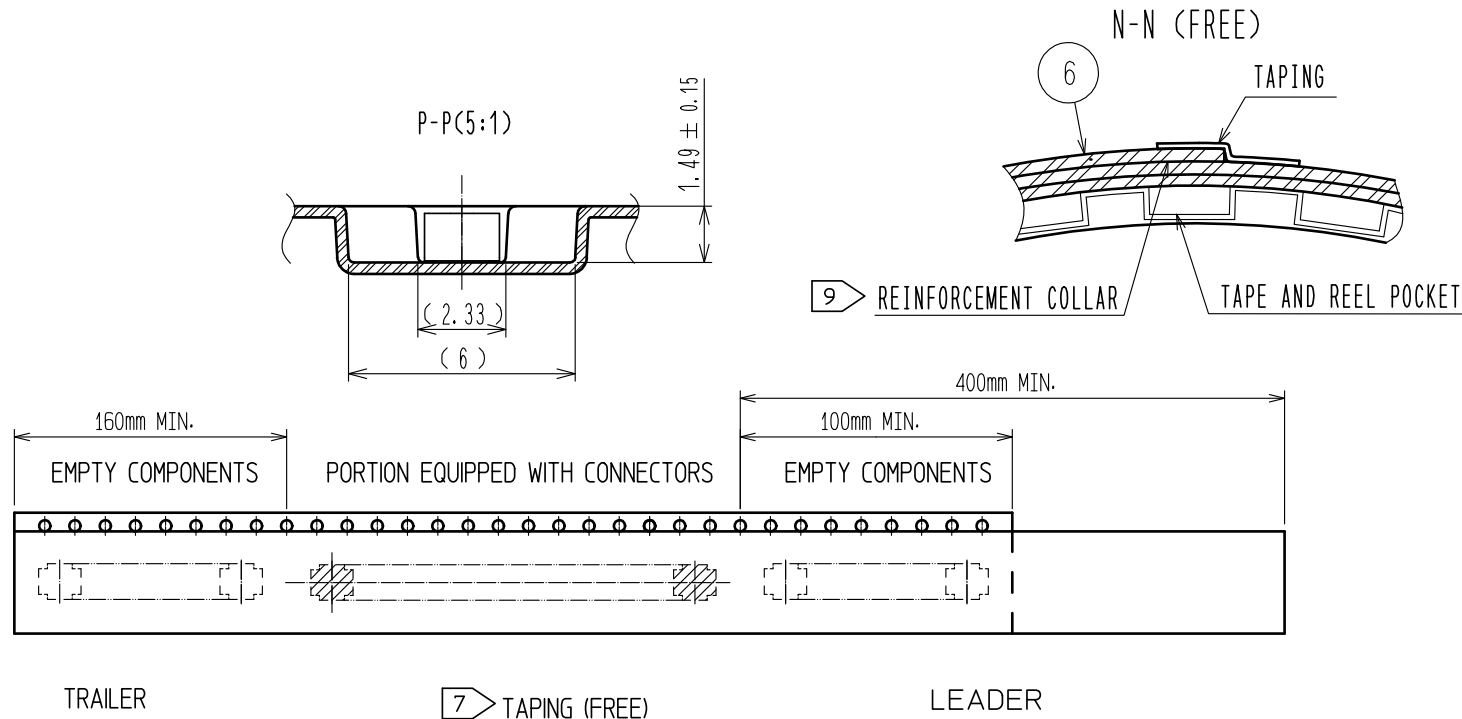


DETAIL OF PART No. LABEL

SUPPLIER	
QUANTITY	
PART No.	
CODE No.	
DATE OF MANUFACTURED	
製造年月日	** ** *
製品コード	CL684-****-51
製品名	BM14EC(1.3)-*DS-0.4V(51)
数量	5,000
納入者	ヒロセ電機(株)

PART No.	F	G	H	J	K	L
BM14EC(1.3)-14DS-0.4V(51)	16	7.5	2.58	4.7	17.5	21.5
BM14EC(1.3)-16DS-0.4V(51)	16	7.5	2.98	5.1	17.5	21.5
BM14EC(1.3)-24DS-0.4V(51)	16	7.5	4.58	6.7	17.5	21.5
BM14EC(1.3)-28DS-0.4V(51)	16	7.5	5.38	7.5	17.5	21.5
BM14EC(1.3)-34DS-0.4V(51)	24	11.5	6.58	8.7	25.5	29.5
BM14EC(1.3)-44DS-0.4V(51)	24	11.5	8.58	10.7	25.5	29.5
BM14EC(1.3)-54DS-0.4V(51)	24	11.5	10.58	12.7	25.5	29.5
BM14EC(1.3)-64DS-0.4V(51)	24	11.5	12.58	14.7	25.5	29.5

5. PER REEL 5000 CONNECTORS.
6. THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.
7. REFER TO JIS C 0806 AND IEC 60286-3
(PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
8. <DELETED>
9. AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET, AND TAPE DOWN AT THE END THE COLLAR.



DRAWING NO.	EDC3-327823-01
PART NO.	BM14EC(1.3)-*DS-0.4V(51)
CODE NO.	CL684